



Material Content Data Sheet



Sales Product Name	IPD50N10S3L-16			Issued		21. September 2015		
MA#	MA001384120							
Package	PG-TO252-3-11			Weight*		372.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.497	1.21	1.21	12071	12071
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		578	
	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	copper	7440-50-8	215.017	57.70	57.78	577143	577894
wire	non noble metal	aluminium	7429-90-5	3.859	1.04	1.04	10358	10358
encapsulation	organic material	carbon black	1333-86-4	1.218	0.33		3270	
	plastics	epoxy resin	-	21.319	5.72		57225	
	inorganic material	silicondioxide	60676-86-0	99.287	26.65	32.70	266504	326999
leadfinish	non noble metal	tin	7440-31-5	3.787	1.02	1.02	10164	10164
plating	non noble metal	nickel	7440-02-0	0.091	0.02		244	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	245
solder	noble metal	silver	7440-22-4	0.100	0.03		268	
	non noble metal	tin	7440-31-5	0.080	0.02		215	
	non noble metal	lead	7439-92-1	3.816	1.02	1.07	10243	10726
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		52	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	copper	7440-50-8	19.177	5.15	5.16	51476	51543
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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